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Siliup Semiconductor

SP60N03HTQ

60V N-Channel Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
60V	3mΩ@10V	130A

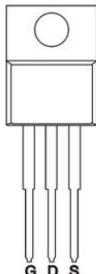
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

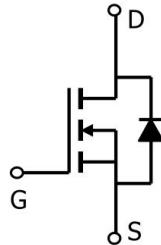
- Power switching application
- DC-DC Converter
- Power Management

Package

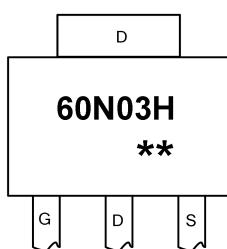


TO-220(G:1 D:2 S:3)

Circuit diagram



Marking



60N03H : Product code
** : Week code



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Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain source voltage	V _{DS}	60	V
Gate source voltage	V _{GS}	±20	V
Continuous drain current(Tc=25°C)	I _D	130	A
Pulsed drain current	I _{DM}	520	A
Power dissipation(Tc=25°C)	P _D	220	W
Single pulsed avalanche energy1)	E _{AS}	1296	mJ
Thermal resistance, junction-case	R _{θJC}	0.57	°C/W
Operation and storage temperature	T _{stg} , T _j	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	60	-	-	V
Drain Cut-Off Current	I _{DSS}	V _{DS} = 48V, V _{GS} = 0V	-	-	1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±0.1	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.0	3.0	4.0	V
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 75A	-	3	3.8	mΩ
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} = 0V, f = 1.0MHz	-	8520	-	pF
Output Capacitance	C _{oss}		-	687	-	
Reverse Transfer Capacitance	C _{rss}		-	573	-	
Switching Characteristics						
Total Gate Charge	Q _g	VDS=30V , VGS=10V , ID=75A	-	164	-	nC
Gate-Source Charge	Q _{gs}		-	38	-	
Gate-Drain Charge	Q _{gd}		-	61	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 30V, RL=0.4Ω , R _G = 2.5Ω	-	25	-	ns
Rise Time	t _r		-	23	-	
Turn-Off Delay Time	t _{d(off)}		-	90	-	
Fall Time	t _f		-	38	-	
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V

Note:

1. E_{AS} is tested at starting T_j = 25°C, V_{DD}=50V,V_{GS} = 10V,L = 0.5mH, R_g=25mΩ;



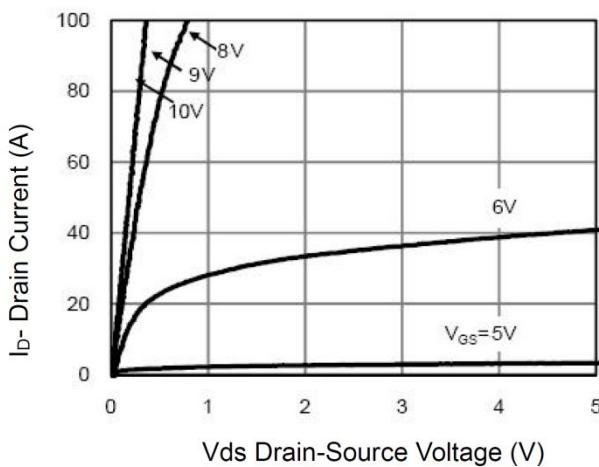
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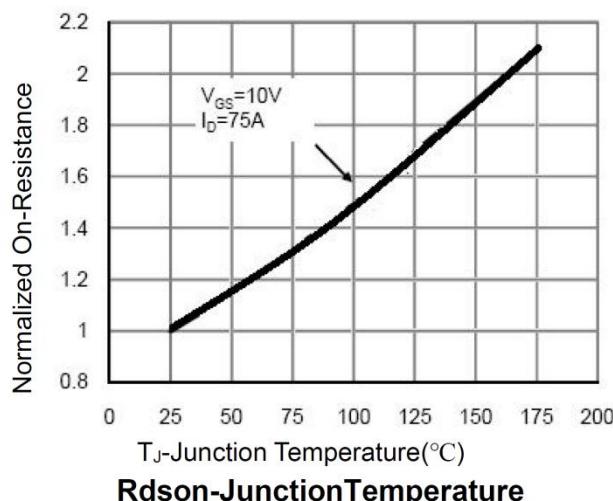
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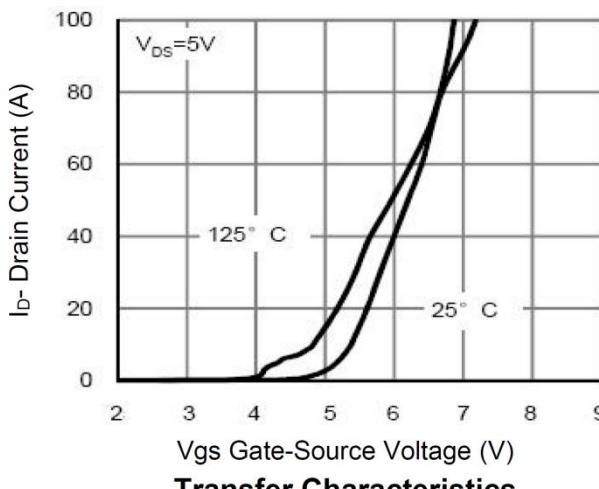
Typical Characteristics



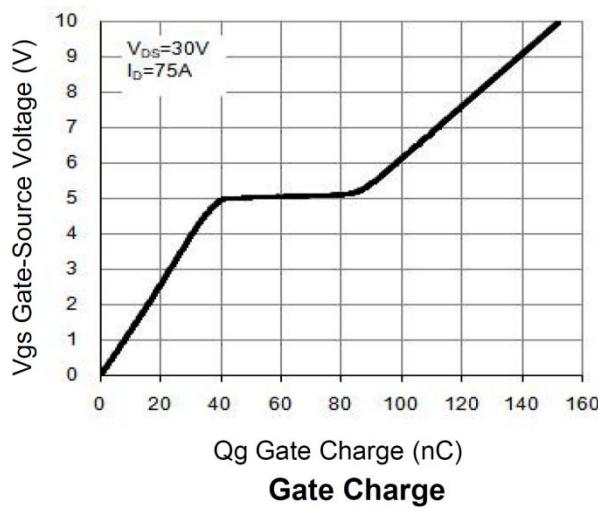
Output Characteristics



Rdson-JunctionTemperature

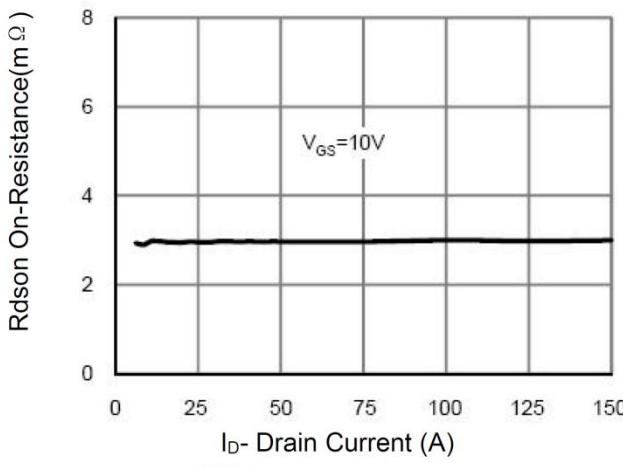


Transfer Characteristics

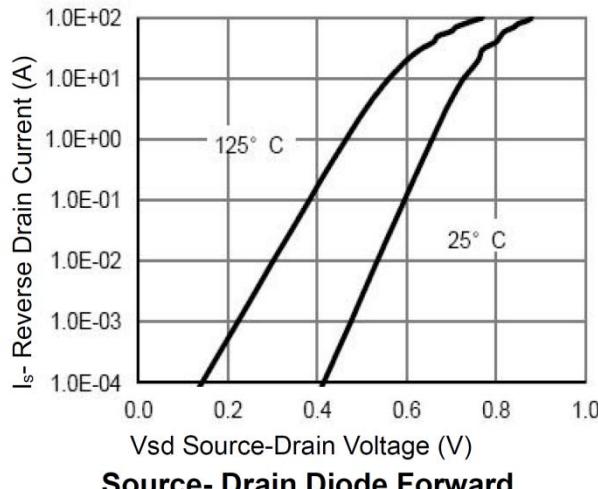


Qg Gate Charge (nC)

Gate Charge



Rdson-Drain Current



Source-Drain Diode Forward

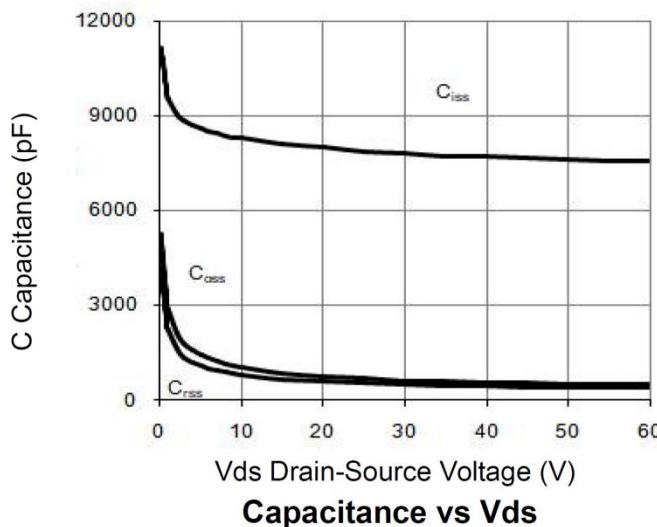


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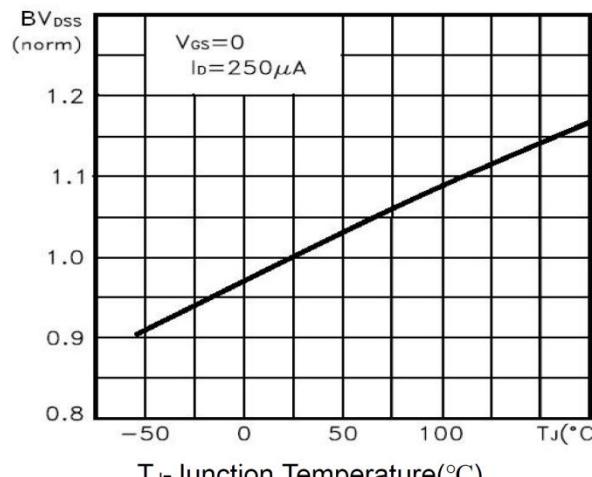
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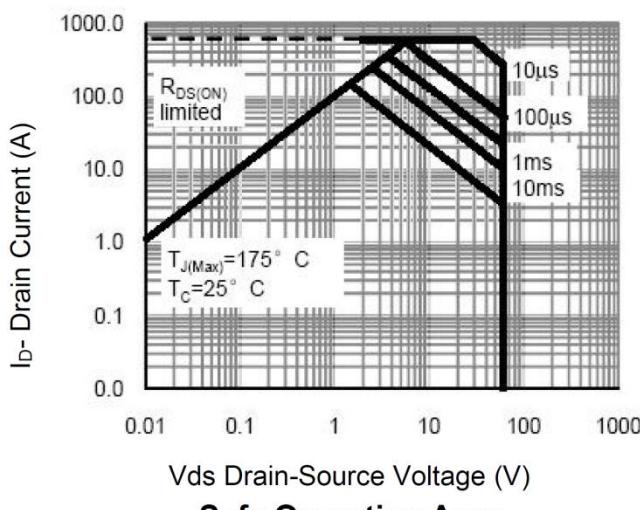
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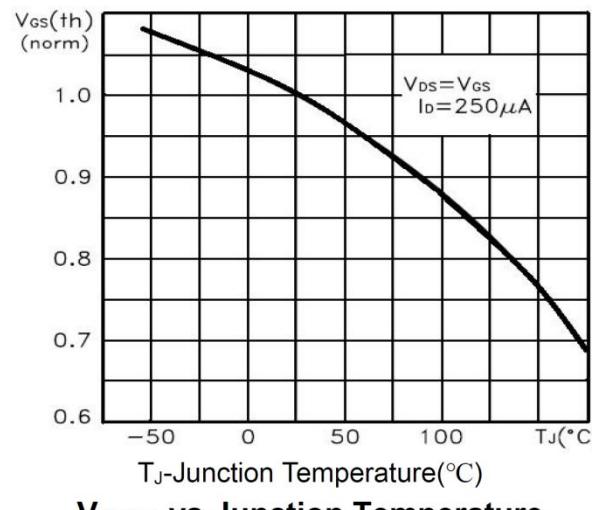
Capacitance vs Vds



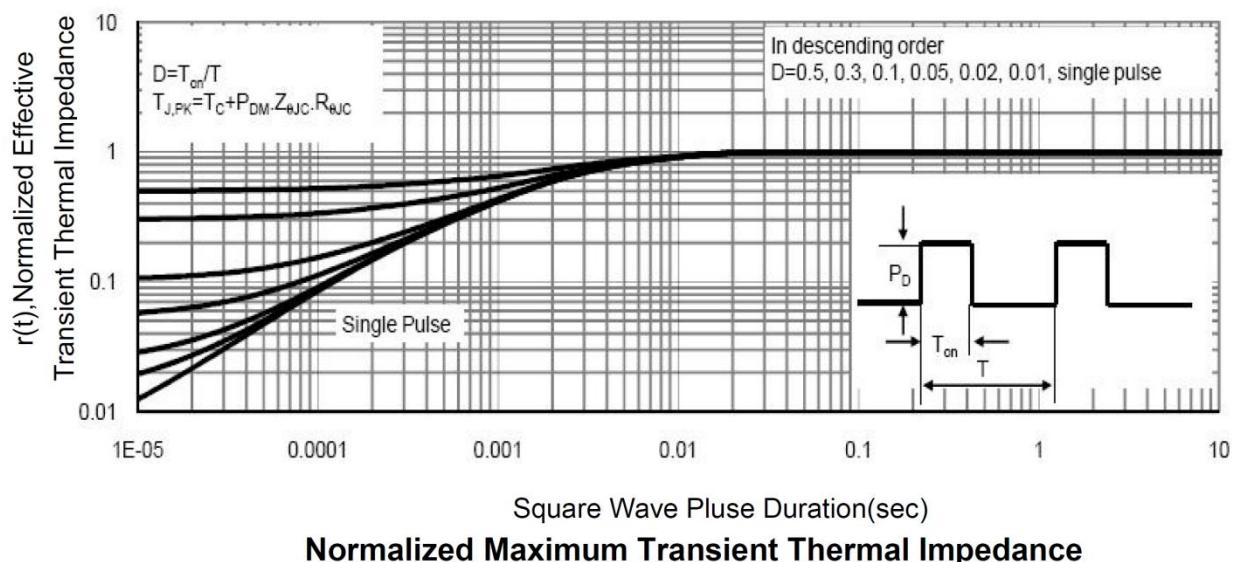
BV_{DSS} vs Junction Temperature



Safe Operation Area



$V_{\text{GS(th)}}$ vs Junction Temperature



Normalized Maximum Transient Thermal Impedance



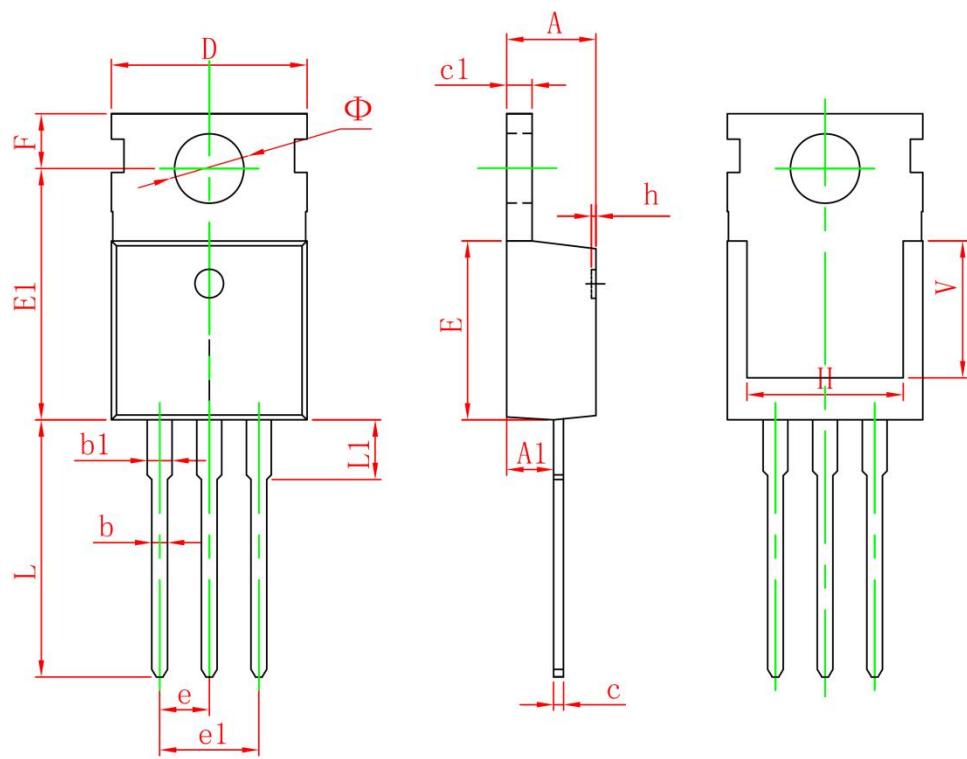
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TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	13.050	0.498	0.514
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150